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Substitute for form 1449A/PTO

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(use as many sheets as necessary)

Sheet 1 of 3

Complete if Known					
Application Number	10/776,076				
Filing Date	February 10, 2004				
First Named Inventor	Madhav Datta				
Art Unit	2813				
Examiner Name	Thanhha S. Pham				
Attorney Docket Number	42P11468D				

			U.S. PATE	NT DOCUMENTS	
Examiner Initials*	Cite No.'	Document Number Number - Kind Code ² (if known)	Publication Date or issue Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
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Examiner Signature	Date Considered	7/18/05

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'Applicant's unique citation designation number (optional). She Kinds Codes of USPTO Patent Documents at www.uspto.gov or MPEP 901.04. Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). Por Japanese patent documents, the Indication of the year of reign of the Emperor must precede the serial number of the patent document. Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible phicant is to place a check mark here if English language Translation is attached.

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Substitute for form 1449AUT IV STATEMENT BY APPLICANT

(use as many sheets as necessary)

Sheet 2 of 3

	Co	mplete if Known	
	Application Number	10/776,076	
	Filing Date	February 10, 2004	
	First Named Inventor	Madhay Datta	
	Art Unit	2813	
_	Examiner Name	Thanhha S. Pham	
	Attorney Docket Number	42P11468D	

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Initials*	No.'	Country Code - Number - Kind Code (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Where Relevant Passages or Relevant Figures Appear	<u> </u>			
						 			
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Examiner		Date	7/10/6
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				Examiner Name	Thanhha S. Pham
Sheet	3	of	3	Attorney Docket Number	42P11468D

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Examiner Initials*	Cite No.¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T*
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Jan. 15, 2000

Examiner Signature		*	Date Considered	7/8/05

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